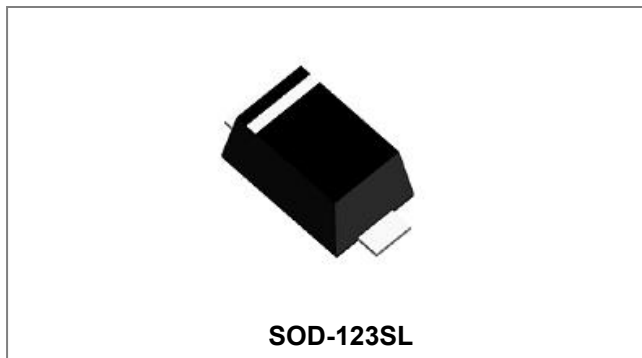


FFM107 SUFACE MOUNT FAST RECOVERY RECTIFIER



Features

- Glass passivated device
- Ideal for surface mouted applications
- Low reverse leakage
- Metallurgically bonded construction
- High temperature soldering guaranteed: 260 C/10 seconds, 0.375" (9.5mm) lead length, 5 lbs. (2.3kg) tension
- Glass passivated chip junction
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: JEDEC SOD-123SL molded plastic
- Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0007 ounce, 0.02 grams

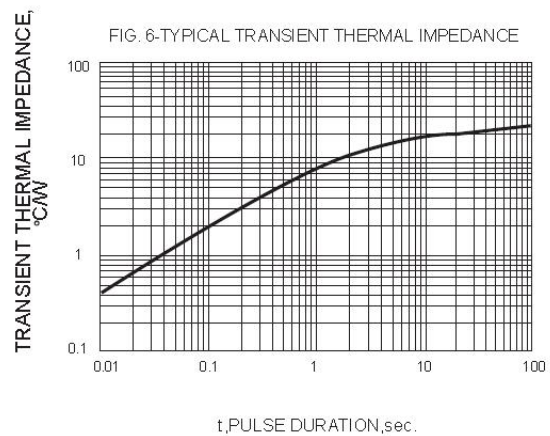
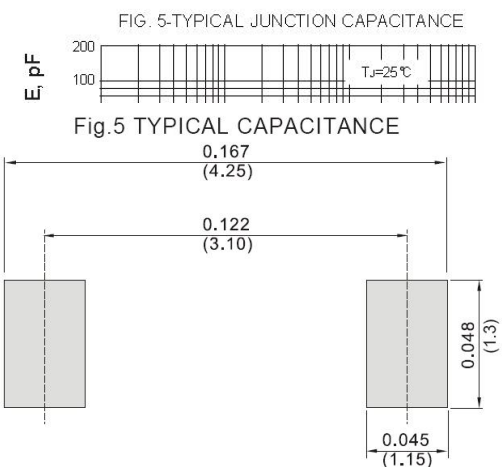
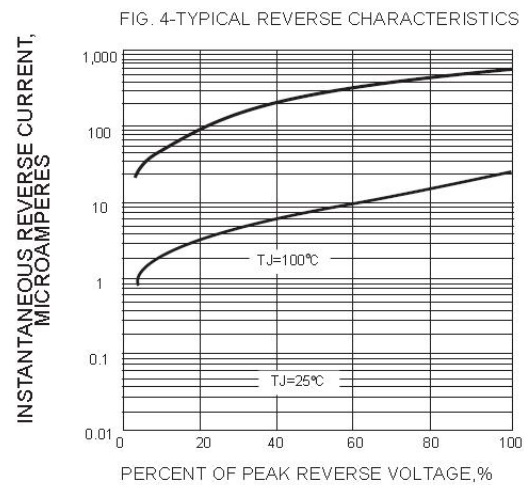
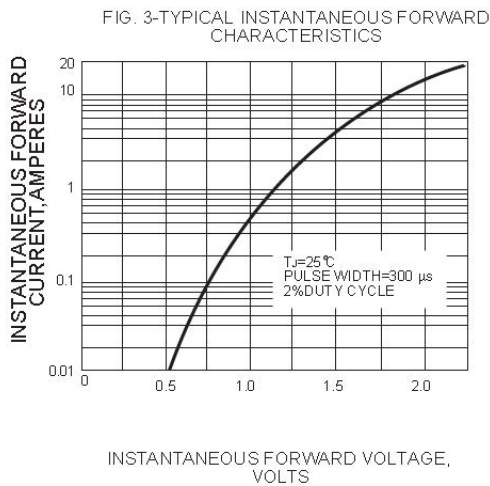
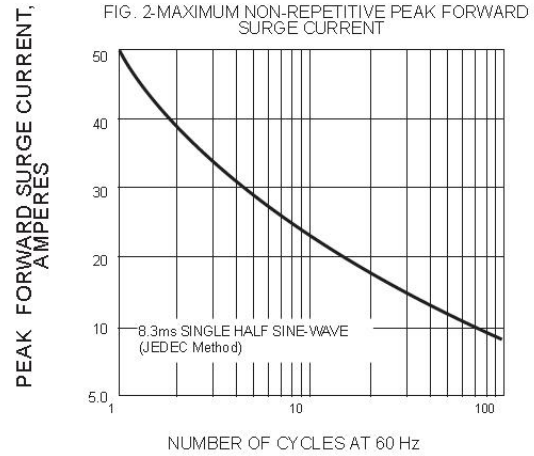
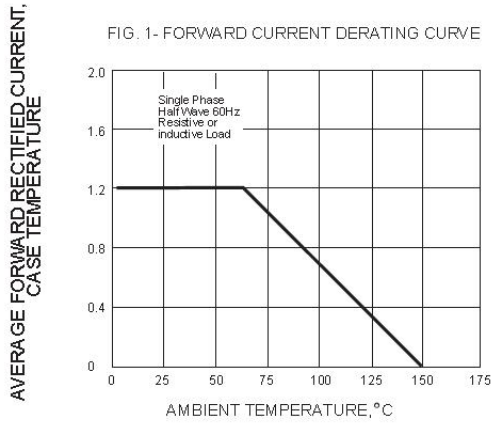
Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

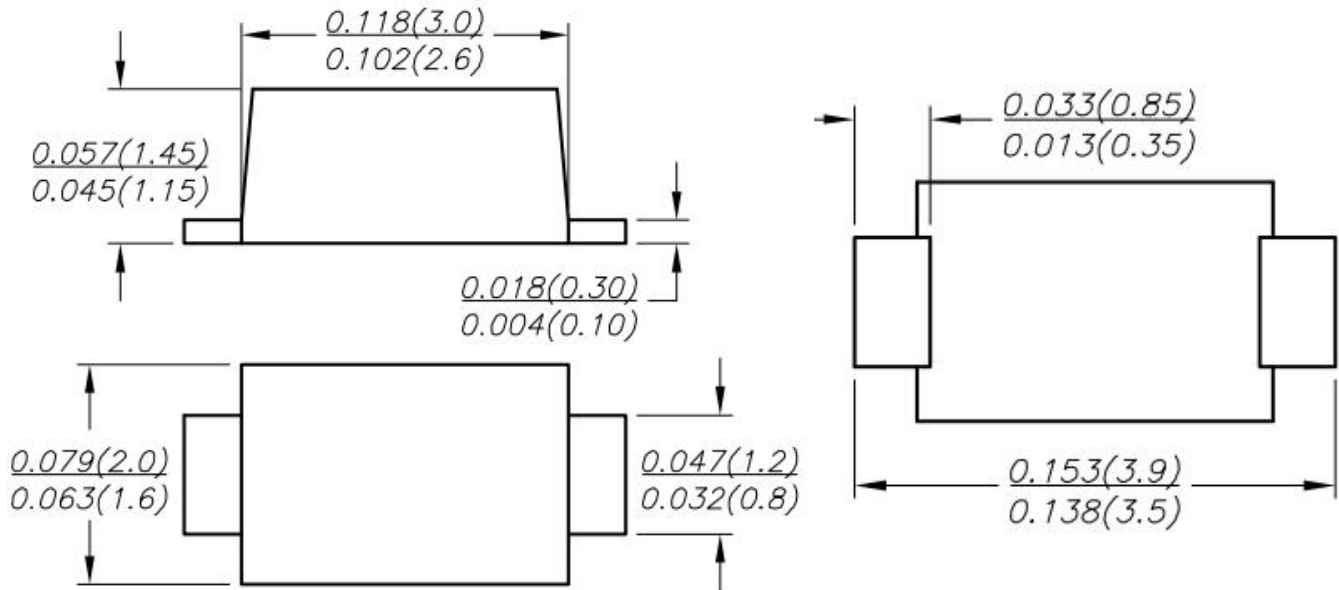
Characteristic	Symbol	FFM107	Units
Maximum repetitive peak reverse voltage Maximum DC blocking voltage	V_{RRM} V_{DC}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum average forward rectified current 0.375"(9.5mm) lead length at @T _A = 65°C	$I_{(AV)}$	1.2	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50	A
Maximum instantaneous forward voltage at 1.2A	V_F	1.3	V
Maximum DC reverse current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I_R	5.0 50.0	μA
Maximum reverse recovery time (Note 2)	t_{rr}	250	ns
Typical Junction Capacitance (Note 3)	C_J	15	pF
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	50	°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	°C

Note: 1. Averaged over any 20ms period.
 2. Measured with I_F=0.5A, I_R=1A, I_{rr}=0.25A.
 3. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings and Characteristics Curves



Mechanical Dimensions SOD-123SL(Inches/Millimeters)

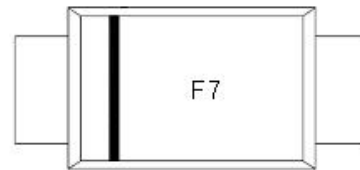


Ordering Information

Device	Package	Shipping
FFM107	SOD-123SL (Pb-Free)	5000pcs / reel

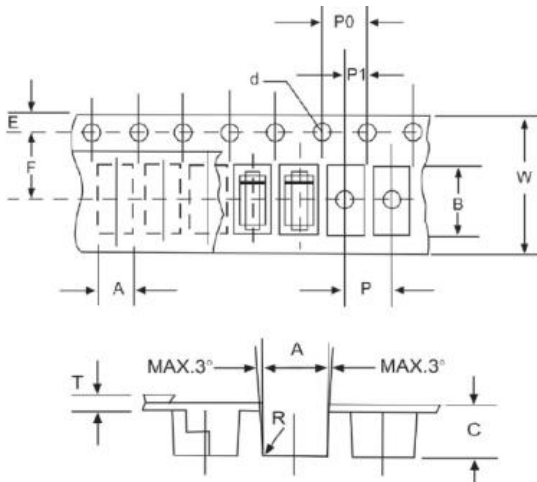
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



F7 = Part Number

Carrier Tape Specification SOD-123SL



SYMBOL	Millimeters	
	Min.	Max.
A	2.05	2.25
B	3.85	4.05
C	1.25	1.45
d	1.45	1.65
E	1.65	1.85
F	3.40	3.60
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
W	7.90	8.30



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